CEP 1 6 100' B)	age <u>1</u>	of <u>1</u>		
FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE	Atty. Docket No.:	Appl'n No.:		
(Rev 8/83) U.S. SEPARTMENT OF COMMERCE  (Rev 8/83) PARENT AND TRADEMARK OFFICE	ELG056-US	10/720,421		
TRADEM!	Applicant:			
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<sup>\*</sup> EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.